

N-Channel Enhancement Mode Power MOSFET

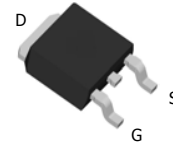
General Features

- $V_{DS} = 60V$, $I_D = 20A$
 $R_{DS(ON)} = 30m\Omega$ (typ) @ $V_{GS} = 10V$
 $R_{DS(ON)} = 35m\Omega$ (typ) @ $V_{GS} = 4.5V$
- High density cell design for ultra low $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

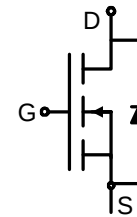
Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

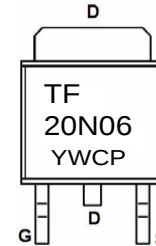
TO-252



Equivalent Circuit



MARKING



Y :year code W :week code

Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	20	A
Drain Current-Continuous($T_C = 100^\circ C$)	$I_D(100^\circ C)$	12	A
Pulsed Drain Current	I_{DM}	60	A
Maximum Power Dissipation	P_D	30	W
Derating factor		0.5	W/ $^\circ C$
Single pulse avalanche energy ^(Note 5)	E_{AS}	60	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	$^\circ C$



Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	$R_{\theta JC}$	5.5	$^{\circ}\text{C/W}$
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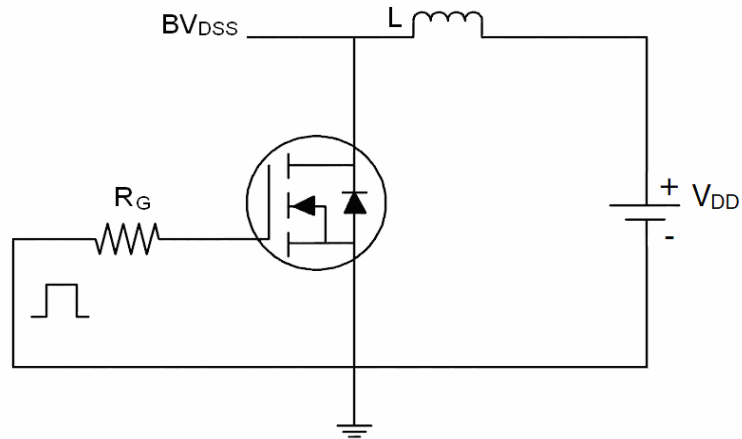
Electrical Characteristics ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	60	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.2	1.6	2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =10A	-	30	35	mΩ
		V _{GS} =4.5V, I _D =10A		35	40	
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =10A	10	-	-	S
Dynamic Characteristics ^(Note4)						
Input Capacitance	C _{iss}	V _{DS} =30V, V _{GS} =0V, F=1.0MHz	-	1234	-	PF
Output Capacitance	C _{oss}		-	70.5	-	PF
Reverse Transfer Capacitance	C _{rss}		-	58.8	-	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =30V, R _L =3Ω V _{GS} =10V, R _G =3Ω	-	13.5	-	nS
Turn-on Rise Time	t _r		-	3.6	-	nS
Turn-Off Delay Time	t _{d(off)}		-	28.8	-	nS
Turn-Off Fall Time	t _f		-	3.2	-	nS
Total Gate Charge	Q _g	V _{DS} =30V, I _D =10A, V _{GS} =10V	-	33.5	-	nC
Gate-Source Charge	Q _{gs}		-	35.0	-	nC
Gate-Drain Charge	Q _{gd}		-	4.7	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V _{SD}	V _{GS} =0V, I _S =10A	-	0.89	1.2	V
Diode Forward Current ^(Note 2)	I _S		-	-	10	A
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F =10A di/dt = 100A/μs ^(Note3)	-	21	-	nS
Reverse Recovery Charge	Q _{rr}		-	17.8	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

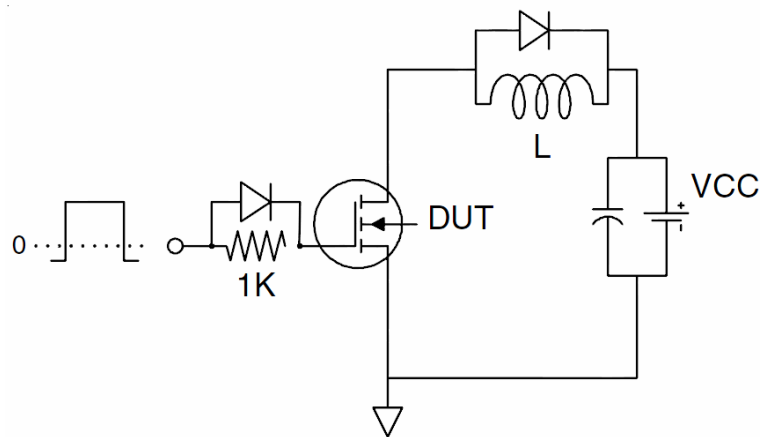
Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition: $T_J=25^{\circ}\text{C}$, $V_{DD}=30V$, $V_G=10V$, $L=0.5mH$, $R_g=25\Omega$

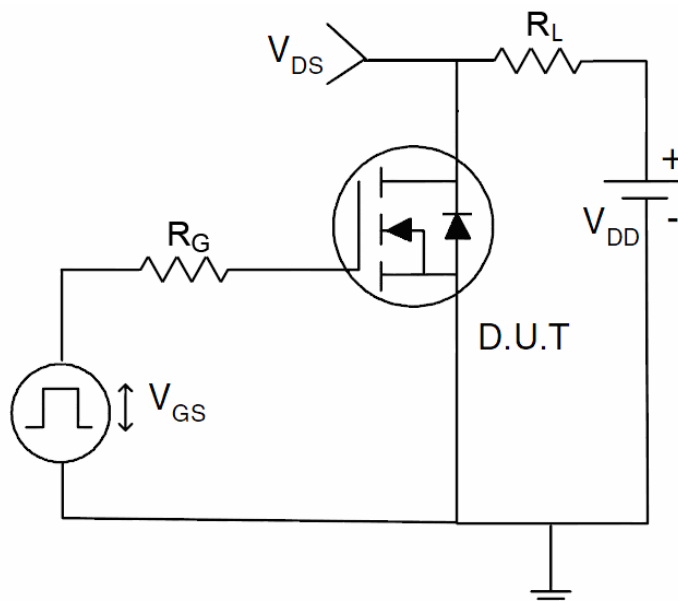
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics (Curves)

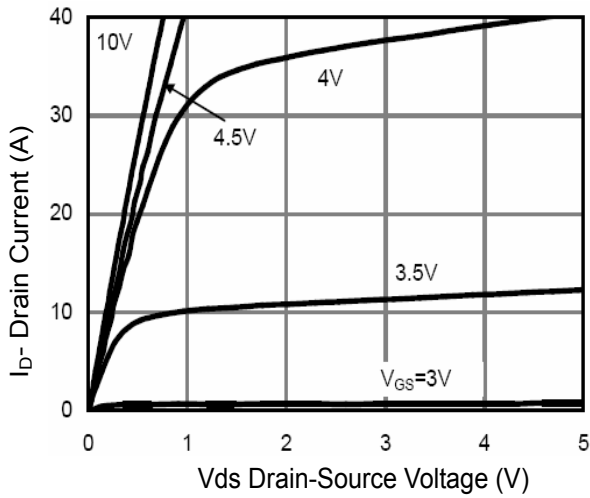


Figure 1 Output Characteristics

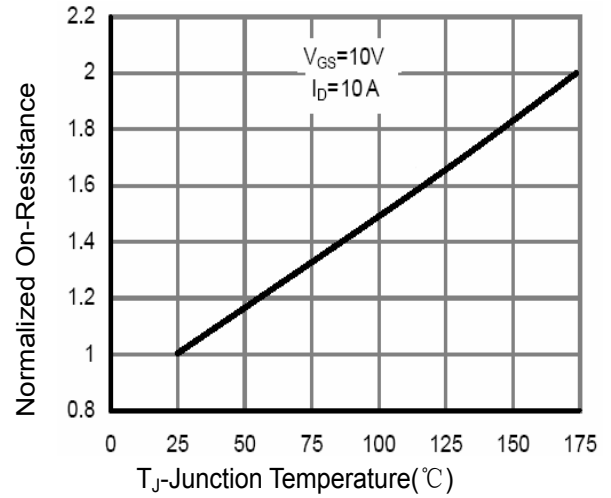


Figure 4 Rdson-Junction Temperature

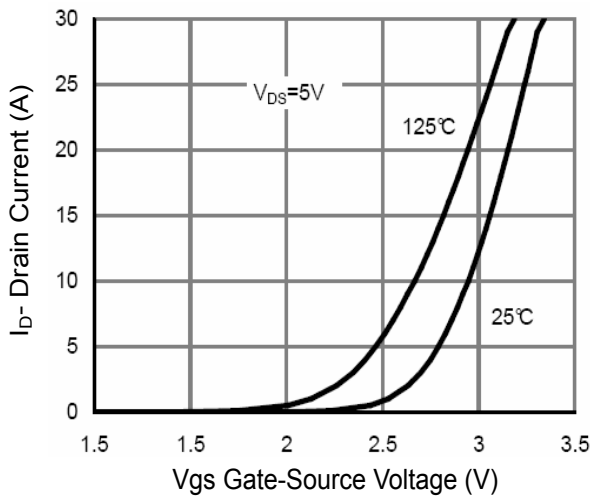


Figure 2 Transfer Characteristics

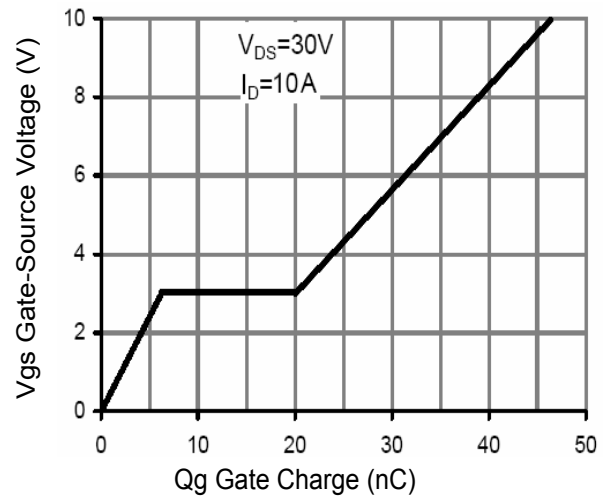


Figure 5 Gate Charge

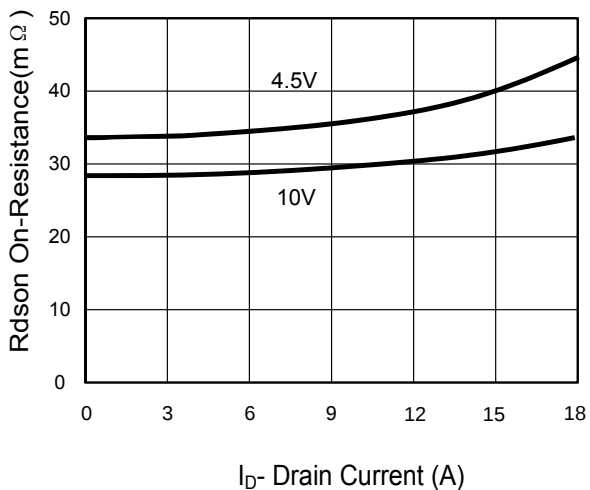


Figure 3 Rdson- Drain Current

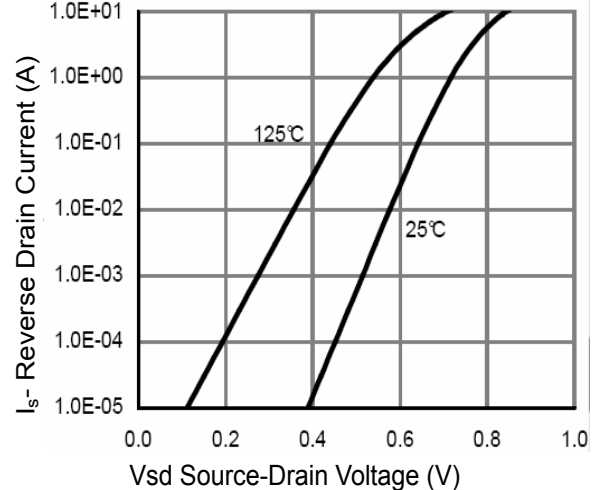


Figure 6 Source- Drain Diode Forward

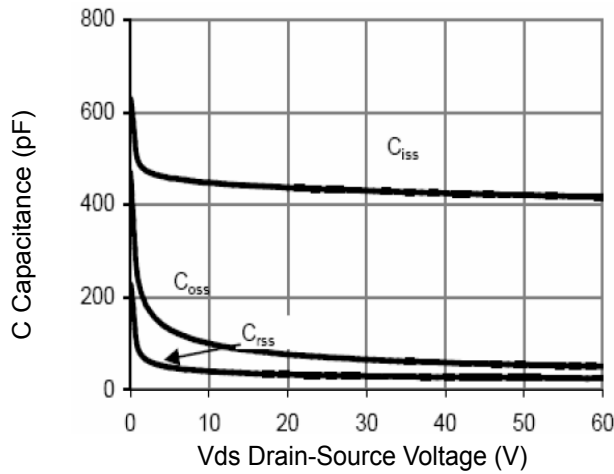


Figure 7 Capacitance vs Vds

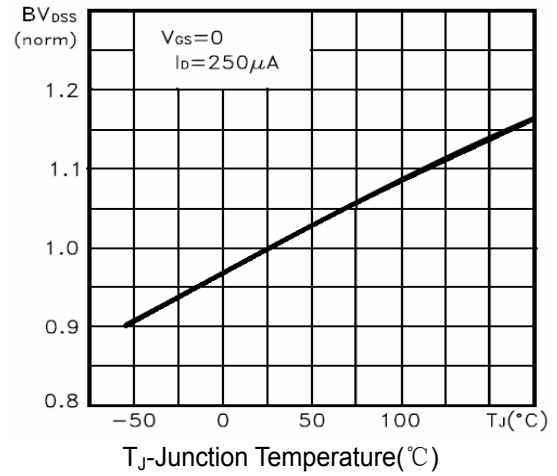


Figure 9 BV_{DSS} vs Junction Temperature

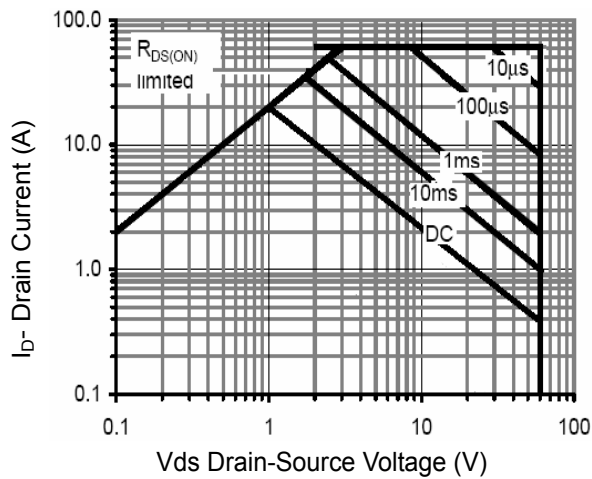


Figure 8 Safe Operation Area

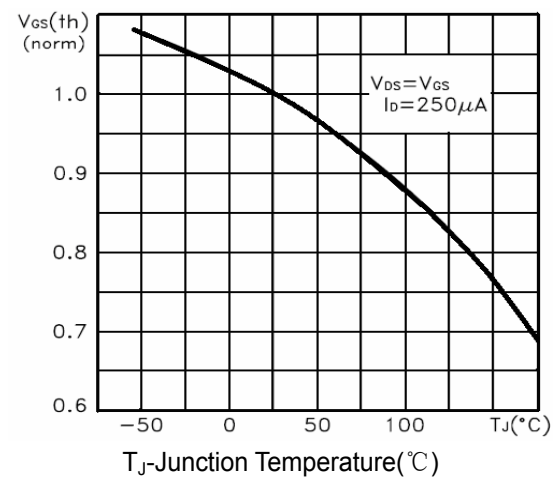


Figure 10 V_{GS(th)} vs Junction Temperature

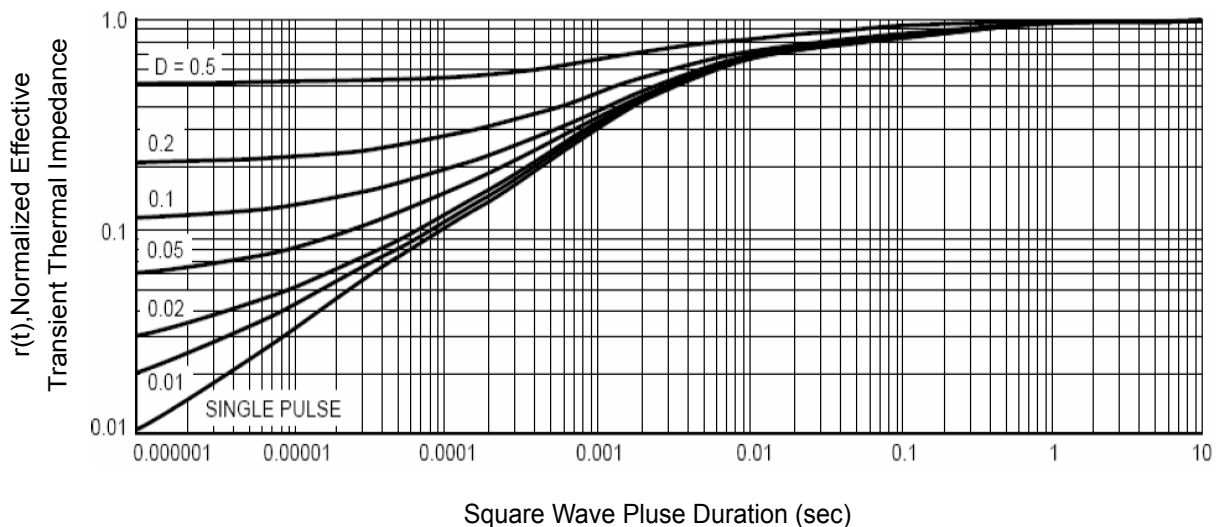
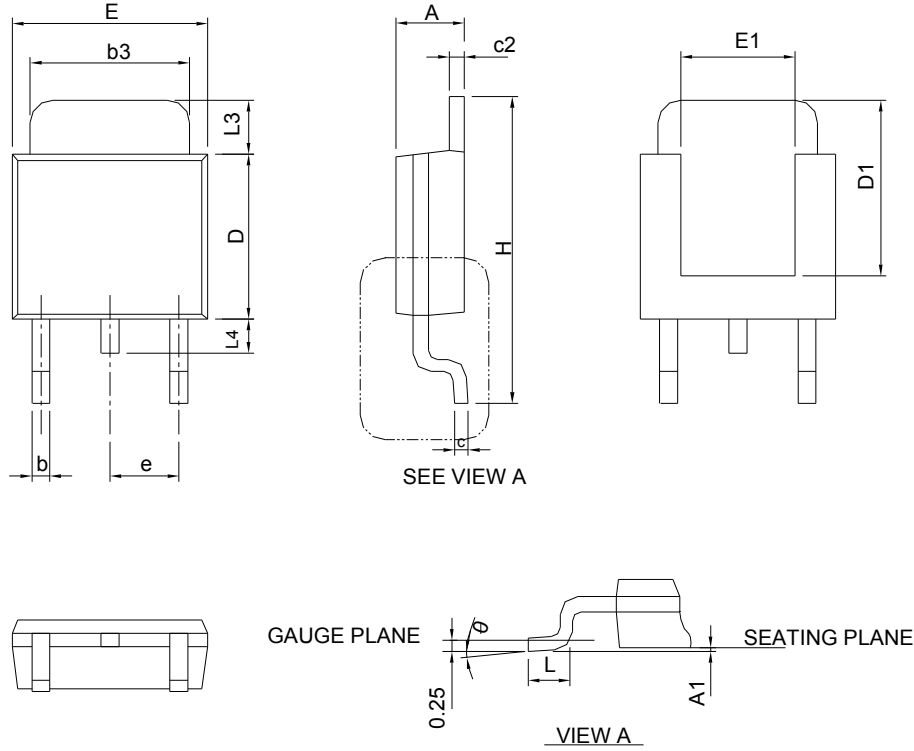


Figure 11 Normalized Maximum Transient Thermal Impedance

Package Information

TO-252-2L



SYMBOL	TO-252-3			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.18	2.39	0.086	0.094
A1		0.13		0.005
b	0.50	0.89	0.020	0.035
b3	4.95	5.46	0.195	0.215
c	0.46	0.61	0.018	0.024
c2	0.46	0.89	0.018	0.035
D	5.33	6.22	0.210	0.245
D1	4.57	6.00	0.180	0.236
E	6.35	6.73	0.250	0.265
E1	3.81	6.00	0.150	0.236
e	2.29 BSC		0.090 BSC	
H	9.40	10.41	0.370	0.410
L	0.90	1.78	0.035	0.070
L3	0.89	2.03	0.035	0.080
L4		1.02		0.040
θ	0°	8°	0°	8°

RECOMMENDED LAND PATTERN

